Intel® Server Board SE7501WV2
Memory List Test Report Summary

Revision 33.0
August, 2004

Revision History		
Date	**Rev**	**Modifications**
Nov/02	0.5	Initial post-launch release for review.
Dec/02	1.0	Released document.
Jan/03	2.0	Added Dataram 1GB parts. Added Avant, Aved, Dataram 512MB parts. Added Samsung 256MB & 512MB parts. Added Netlist 512MB part. (In shaded area)
Jan/03	3.0	Added Micron 128MB part. Made changes to the verbiage in the product description page. (In shaded area)
Feb/03	4.0	Added Infineon 512MB & 1G parts. (In shaded area) Removed Samsung 512MB and 1G parts.
Feb/03	5.0	Added ATP, Corsair 1GB parts. Added Avant, Corsair, Dataram, Simple, Ventura, Virtium 512MB parts. Added Viking 256MB parts. (In shaded area)
Mar/03	6.0	Added Avant & Dataram 1GB parts. Added Avant & Viking 512MB parts. Added ATP & Viking 256MB parts. Added Samsung 1G parts. (In shaded area)
Mar/03	7.0	Added Samsung, MSC Vertriebs & Buffalo 512MB parts. Added Netlist & Avant 1G parts. (In shaded area)
Mar/03	8.0	Added ATP 128MB part. Added ATP & Viking 256MB parts. Added ATP, Southland & Viking 512MB parts. Added Netlist, Aved, ATP, Dataram & Southland 1GB parts. Added Micron 256MB & 512MB parts. Added Infineon & Samsung 128MB, 256MB, 512MB & 1G parts. (In shaded area)
April/03	9.0	Added Centon 256MB parts. Added Smart 512MB parts. Added Avant, ATP & Micron 1GB parts. (In shaded area)
Apr/03	10.0	Added Netlist & Centon 1GB parts. Added Infineon , Dataram & Buffalo 256MB parts. Added Micron 256MB and 512MB parts. Added Viking & Simple 512MB parts. (In shaded area)
June/03	11.0	Added Buffalo and ATP 256MB parts. Added Viking, Buffalo, Corsair and ATP 512MB parts. Added Simple 1GB parts. Added Micron 128MB part. Added Samsung 512MB & 1G parts. (In shaded area)
June/03	12.0	Added Viking and Buffalo 256MB parts. Added Smart 1GB and 2GB parts. (In shaded area). Added Samsung 256, 512MB, 1G & 2G parts. Added Infineon 512MB, 1G & 2G parts. Added verbiage for 2G-module support. Updated EOL status.
July/03	13.0	Added TRS 256MB parts. Added TRS, Legend and PMI 512MB parts. Added Samsung, PMI and Centon 1GB parts.
July/03	14.0	Added Itaucom and legend 512MB parts. Added Smart, Buffalo, PMI, Itaucom and legend 1GB parts. Added Micron 512MB & 1G parts. (In shaded area)
Aug/03	15.0	Added Infineon 256MB part. Added Smart 512MB parts. Added Buffalo, Micron & Centon 1GB parts. (In shaded area) Also Updated EOL status.
Sept/03	16.0	Added Smart & Samsung 512MB & 1GB parts. (In shaded area)
Sept/03	17.0	Added Avant 512MB parts. Added Centon & Ventura 1GB parts. Added Infineon & Micron 256MB & 512MB parts. Add (In shaded area)
Oct/03	18.0	Added Avant & Smart 512MB modules. Added TRS 1GB parts. Added TRS 2GB parts. (In shaded area). Also updated EOL status.
Nov/03	19.0	Added Ventura 512MB parts. Added Wintec, Virtium, & legend 1GB parts. Added Micron 256MB part. Correction made for Samsung 256MB part. (In shaded area)
Nov/03	20.0	Added Legend 256MB parts. Added Legend, Centon, ATP & Smart 512MB parts. Added Avant, Viking & Smart 1GB parts. Added Avant, Smart & Dataram 2GB parts. Added Kingston 256MB & 512MB parts. (In shaded area)
Nov/03	21.0	Added ATP 1GB parts. Added Legacy 512MB, 1GB and 2gb parts. (In shaded area)
Dec/03	22.0	Added ATP, Apacer and Legend 1GB parts. Added Kingston 128MB part. Updated “Note” regarding mix-memory support. (In shaded area)
Jan/04	23.0	Added Smart 1GB parts. (In shaded area)
Feb/04	24.0	Added PMI and Centon 1GB parts. Added ATP & Samsung 2GB parts. (In shaded area). Also updated EOL status.
Feb/04	25.0	Added Dane-elec 256MB parts. Added Smart, Swissbit and Buffalo 1GB parts. Added Dataram and Micron 2GB parts. New CMTL address. (In shaded area)
Mar/04	26.0	Added Swissbit 512MB parts. Added Smart and TRS 1GB parts. (In shaded area)
Mar/04	27.0	Added Ventura 512MB parts. Added TRS, Ventura, and Dataram 1GB parts. (In shaded area). Also Updated EOL status.

Revision History		
Date	**Rev**	**Modifications**
Mar/04	27.1	Added Samsung 1G part. (In shaded area).
Apr/04	28.0	Added Netlist 512MB parts. Added Ventura, Legacy and Smart 1GB parts. Added Ventura 2GB parts. (In shaded area)
May/04	29.0	Added Legacy 1GB and 2GB parts. Added Viking, and ATP 1GB parts. (In shaded area)
Jun/04	30.0	Added Samsung & Micron 256MB parts. Added Legacy and Viking 512MB parts. Added Corsair, Samsung, Infineon & Micron 1GB parts. Added Samsung & Micron 2G parts. (In shaded area)
Jun/04	31.0	Added Ventura 512MB parts.
July/04	32.0	Added Legacy 256MB parts. Added Kingston 1GB and 2GB parts. (In shaded area)
Aug/04	33.0	Added Netlist 256MB parts. Added Dane-Elec 512MB parts. Added Dataram 1GB parts. (In shaded area)

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The hardware vendor remains solely responsible for the design, sale and functionality of its product, including any liability arising from product infringement or product warranty. Only approved software drivers and accessories that are recommended for the revision number of the boards and system being operated should be used with Intel products. Please note that, as a result of warranty repairs or replacements, alternate software and firmware versions may be required for proper operation of the equipment.

The Intel® Server Board SE7501WV2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

* Other brands and names are the property of their respective owners.

Please Note: *DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended*

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Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7501WV2. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)[1]. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel®'s Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft* Windows* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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[1] CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690
Fax (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
http://www.cmtlabs.com/

Qualified Memory for the Intel® Server Board SE7501WV2

The memory module on the server board SE7501WV2 has 6 DIMM sockets, which can hold up to 12 GB of Registered DDR266 memory using six 72-bit DIMM modules. The following memory features are supported:

- DDR266 registered ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMMs with capacity of 128MB, 256MB, 512MB, 1G and 2G. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 256MB using two 128MB DIMM.

The memory controller in the E7501 chip set supports memory scrubbing, single-bit error correction and multiple-bit error detection and the Intel® Single Device Data Correction feature. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs. The Intel® Single Device Data Correction architecture gives the memory sub-system the ability to withstand a multibit failure within a DRAM device, including a failure that causes incorrect data on all data bits of the device.

> **Note:** *Intel does not test all possible combinations of mixed memory modules within the same server system. Functionality issues may occur if mixed memory types are installed in the same server system. Intel recommends that memory modules of identical size, type, banking and stacking technology, and vendor are installed in each server system. Customers who choose to use mixed memory module configurations assume responsibility for ensuring that these configurations are compatible and tested*

Due to the Intel® server board SE7501WV2 DDR 266 DIMM Slew Rate Observation Sighting issue that is documented in TA 639-x, Intel recommends that customers utilize SE7501WV2 BIOS P06 or later versions on the server board SE7501WV2. Please reference TA 639-x for further information on this issue.

Intel does not test, recommend, or support any mixing of memory types within the same server systems. However, if the customer chooses to utilize mixed memory configurations, the following guidelines should be observed: Certain mixed memory configurations violate the Intel® E7501 chipset specification for DDR write ring back when installed in the server board SE7501WV2. Mixed memory configurations with both Double-Banked (DB) and Single-Banked (SB) DIMMs installed require that the SB DIMMs must be installed in the lowest numbered memory slots (memory slots furthest from the MCH – DIMM 1A & DIMM 1B). Mixed memory configurations with SB DIMMs installed in the highest numbered memory slots (memory slots closest to the MCH – DIMM 3A & DIMM 3B) and DB DIMMs installed in the lowest numbered memory slots are detected by the SE7501WV2 BIOS, and a POST error message will be displayed instructing the user to reorder their DIMM pairs. The following mixed memory configurations will cause the BIOS to display a POST error message when installed:

DIMM 1A & 1B	**DIMM 2A & 2B**	**DIMM 3A & 3B**	
DB	SB	Empty	Invalid: violates write ring back spec
DB	DB	SB	Invalid: violates write ring back spec
DB	SB	SB	Invalid: violates write ring back spec
DB	SB	DB	Invalid: violates write ring back spec
SB	DB	SB	Invalid: violates write ring back spec
Empty	Empty/SB/DB	Empty/SB/DB	Invalid: DIMMs must be populated starting with pair 1A/1B, then 2A/2B, then 3A/3B
SB/DB	Empty	SB/DB	Invalid: DIMMs must be populated starting with pair 1A/1B, then 2A/2B, then 3A/3B

How to identify if you have "Single-Banked" or "Double-Banked" modules:

- ***x8SB*** = *x8 Single-Banked modules* - have 5 DRAM's on the front and 4 DRAM's on the back with empty spots in between the DRAM's.
- ***x8DB*** = *x8 Double-Banked modules* - have 9 DRAM's on each side for a total of 18 (no empty slots)
- ***x4SB =*** *x4 Single-Banked modules* - have 9 DRAM's on each side for a total of 18 – and look similar to x8 double-banked
- ***x4DB =*** *x4 Double-Banked modules* - have 18 (stacked) DRAM's on each side for a total of 36

Below is a chart that lists the current supported memory types:

DDR266 Registered DRAM Module Configurations for Cas Latency 2					
DIMM Capacity	**DIMM Organization**	**DRAM Density**	**DRAM Organization**	**# DRAM Devices/rows/Banks**	**# Address bits rows/Banks/column**
128MB	16M x 72	64Mbit	16M x 4	18/1/4	12/2/10
128MB	16M x 72	64Mbit	8M x 8	18/2/4	12/2/9
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	64Mbit	16M x 4	36/2/4	12/2/10
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	128Mbit	32M x 4	36/2/4	12/2/11
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12

Memory features are detailed in *the Intel® Server Board SE7501WV2 Technical Product Specification* available on-line at http://support.intel.com/support/motherboards/server/SE7501WV2

The following tables list DIMM devices known to be compatible with the Intel Server Board SE7501WV2. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

This list is subject to change without notice.

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Samsung	M383L1713DTS-CA2	K4H280838D-TCA2	Samsung		10/15/02	2		(16Mx8) *9	x8SB	
Samsung	M312L1713DT0-CA2	K4H280838D-TCA2	Samsung		11/14/02	2	Yes	(16Mx8) *9	x8SB	
Infineon	HYS72D16500GR-7-A	HYB25D128800AT-7	Infineon		12/18/02	2	Yes	(16Mx8) *9	x8SB	
Micron	MT9VDDT1672G-265B2	MT46V16M8-75 B	Micron		1/1/03	2.5	Yes	(16Mx8) *9	x8SB	
+ATP Electronics	AB16L72A8SEB0S	K4H280838D-TCB0 rev D	Samsung	SB184A08L rev 1	1/3/03	2.5		(16Mx8) *9	x8SB	EOL
Samsung	M383L1713ETS-CB0	K4H280838E-TCB0	Samsung		1/28/03	2.5		(16Mx8) *9	x8SB	
Infineon	HYS72D16000GR-7-A	HYB25D128800AT-7A	Infineon		3/11/03	2		(16Mx8) *9	x8SB	
Samsung	M312L1713ETS-CA2	K4H280838E-TCA	Samsung		3/26/03	2	Yes	(16Mx8) *9	x8SB	
Micron	MT9VDDT1672G-265B1	MT46V16M8-75 B	Micron		5/2/03	2.5		(16Mx8) *9	X8SB	
Kingston	KVR266X72RC25/128	HY5DU28822BT-H	Hynix		12/8/03	2.5	Yes	(16Mx8) *9	X8SB	

Modules shaded in blue are low profile

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards. For further information contact CMTL @ http://cmtlabs.com/

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Apacer	Apacer 75.85380.790	HYB25D256800BT-7	Infineon		10/25/02	2	Yes	(32Mx8)*9	x8SB	
Samsung	M312L3310DT0-CA2	K4H280438D-TCA2	Samsung		11/18/02	2	Yes	(32Mx4)*18	x4SB	
Samsung	M383L3310DTS-CA2	K4H280438D-TCA2	Samsung		12/06/02	2		(32Mx4)*18	x4SB	
Samsung	? M312L3223DT0-CAA	K4H560838D-TCAA	Samsung		12/16/02	2	Yes	(32Mx8)*9	x8SB	
+Viking	VI4CR327224CTHL1	K4H280438D-TCB0 rev D	Samsung	03-0291 Rev A	12/30/02	2.5	Yes	(32Mx4)*18	x4SB	EOL
+ATP Electronics	AB32L72A8S4B0	NT5DS16M8AT-7K rev D	Nanya	SB184A08L rev 1	12/30/02	2.5		(16Mx8)*18	x8DB	EOL
Infineon	? HYS72D32300GBR-7F-B	HYB25D256800BC-7F	Infineon		2/08/03	2	Yes	(32Mx8)*9	x8SB	
+Viking	VI4CR327228DTHL2	MT46V32M8TG-75 rev B	Micron	0000905A	2/24/03	2.5	Yes	(32Mx8)*9	x8SB	EOL
+ATP Electronics	AB32L72Q8SQB0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1	3/5/03	2.5	Yes	(32Mx8)*9	x8SB	EOL
Infineon	HYS72D32500GR-7-B	HYB25D256800BT-7	Infineon		3/11/03	2	Yes	(32Mx8)*9	x8SB	
Samsung	M383L3310ETS-CB0	K4H280438E-TCB0	Samsung		3/21/03	2.5		(16Mx8)*18	x8DB	
Micron	MT9VDDT3272G-265B2	MT46V32M8-75 B	Micron		3/31/03	2.5	Yes	(32Mx8)*9	x8SB	
+Centon Electronics	TOP02-D007G	MT46V32M4TG-75 rev B	Micron	LE36DDT1844R rev A	4/4/03	2.5	Yes	(32Mx4)*18	x4SB	EOL
Infineon	HYS72D32001GR-7-A	HYB25D128400AT-7A	Infineon		4/3/2003	2.5		(32Mx4)*18	x4SB	
Micron	MT9VDDT3272G-265B1	MT46V32M8-75 B	Micron		4/9/2003	2.5		(32Mx8)*9	x8SB	
+Dataram	DTM63640B	MT46V32M4TG-75 rev B	Micron	40581A rev A	4/15/03	2.5	Yes	(32Mx4)*18	x4SB	
+Buffalo	DD266-R256/SD	K4H280838D-TCB0 rev D	Samsung	RCE0501-AB	4/21/03	2.5		(16Mx8)*18	x8DB	
Micron	MT9VDDT3272G-265C3	MT46V32M8-75 C	Micron		4/22/03	2.5	Yes	(32Mx8)*9	x8SB	
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	5/19/03	2.5	Yes	(32Mx8)*9	x8SB	
+ATP Electronics	AB32L72A8S4B0S	K4H280838D-TCB0 rev D	Samsung	SB184A08L rev1	5/7/03	2.5		(16Mx8)*18	x8DB	EOL
+Viking	VI4CR327228DTHL3	MT46V32M8TG-75 rev C	Micron	0000905A	5/24/03	2.5	Yes	(32Mx8)*9	x8SB	

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Buffalo	DD266-R256/SE	K4H280838E-TCB0 rev E	Samsung	RCE0502-AA	5/30/03	2.5		(16Mx8) *18	x8DB	
Samsung	M312L3223ETS-CA2	K4H560838E-TCCA2	Samsung		6/9/03	2	Yes	(32Mx8) *9	x8SB	
+TRS* Tele-Radio-Space GmbH	TRS21150	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/19/03	2	Yes	(32Mx8) *9	x8SB	
ITAUCOM	256E2665R28	ICM4L560807-65	Micron	0247 A	6/27/03	2.5	Yes	(32Mx8) *9	x8SB	
Infineon	HYS72D32300GBR-7-B	HYB25D256800BC-7	Infineon		8/18/03	2	Yes	(32Mx8) *9	x8SB	
Infineon	HYS72D32000GR-7-B	HYB25D256800BT-7	Infineon		9/8/2003	2		(32Mx8) *9	x8SB	
Micron	? MT9VDDT3272G-262C3	MT46V32M8-6T C	Micron		9/16/2003	2	Yes	(32Mx8) *9	x8SB	
Samsung	? M312L3223ETS-CAA	K4H560838E-TCAA	Samsung		10/30/03	2	Yes	(32Mx8) *9	x8SB	
+Legend	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	10/30/03	2.5	Yes	(32Mx8) *9	x8SB	
Kingston	KVR266X72RC25/256	MT46V32M8-75C	Micron		11/5/03	2.5	Yes	(32Mx8) *9	x8SB	
+Dane-Elec	ODLD266R072325I-1MC	MT46V32M8TG-6T rev C	Micron	DR1G872-A rev A	2/12/04	2.5	Yes	(32Mx8) *9	x8SB	
Micron	MT9VDDT3272G-265G3	MT46V32M8-6T G	Micron		4/5/04	2.5	Yes	(32Mx8) *9	x8SB	
Samsung	? M383L3223DTS-CAA	K4H560838D-TCAA	Samsung		4/12/04	2		(32Mx8) *9	x8SB	
+Smart Modular Technology	SM3272RDDR320LP-I	HYB25D256800BT-7 rev B	Infineon	184-L13-2	8/20/03	2	Yes	(32Mx8) *9	x8SB	
+Legacy Electronics Inc.	87S6EDLR-1JDG	HYB25D128400AT-7 rev A	Infineon	LE36DDT1844R rev A	6/30/04	2.5	Yes	(32Mx4) *18	x4SB	
Netlist, Incorporated	NL9327RD16082-C21J	MT46V16M8TG(P)-75 rev B	Micron	0185-10 rev A	7/22/04	2.5	Yes	(32Mx8) *9	x8SB	

Modules shaded in blue are low profile

? This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards. For further information contact CMTL @ http://cmtlabs.com/

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Apacer	Apacer 75.96280.791	HYB25D256400BT-7	Infineon		10/23/02		Yes	(64Mx4) *18	x4DB	
Samsung	M312L6423DT0-CA2	K4H5608380-TCA2	Samsung		11/01/02		Yes	(32Mx8) *18	x8DB	
Micron	MT18VDDT6472G-265B3	MT46V64M4-75 B	Micron		11/10/02		Yes	(64Mx4) *18	x4SB	
Samsung	M383L6420DTS-CA2	K4H560438D-TCA2	Samsung		11/16/02			(64Mx4) *18	x4SB	
+Avant Technology	AVM7264R38C5266K0-A	K4H560438C-TCB0 rev C	Samsung	50-1415-01 rev B	12/9/02	2.5	Yes	(64Mx4) *18	x4SB	EOL
+Dataram	DTM63641E	HYB25D256400BT-7 rev B	Infineon	40581A rev A	12/16/02	2.5	Yes	(64Mx4) *18	x4SB	EOL
+Aved Memory Products	AMP383D6420CT3-CB0/S	K4H560438C-TCB0 rev C	Samsung	105611 rev A	12/17/02	2.5	Yes	(64Mx4) *18	x4SB	EOL
+MSC Vertriebs GmbH	MSC 512M00098	MT46V32M8TG-75 rev B	Micron	PCB M0481LA2	12/17/02	2.5		(32Mx8) *18	x8DB	EOL
+ATP Electronics	AB64L72A8S8B0	NT5DS32M8AT rev D	Nanya	SB184A08L rev1	12/19/02	2.5		(32Mx8) *18	x8DB	EOL
Samsung	M312L6420DT0-CA2	K4H560438D-TCA2	Samsung		12/20/02	2	Yes	(64Mx4) *18	x4SB	
Infineon	HYS72D64500GR-7-B	HYB25D256400BT-7	Infineon		12/20/02	2	Yes	(64Mx4) *18	x4SB	
Netlist	NL9647RD64042-D21J	K4H560438D-TCB0	Samsung		12/27/02	2.5	Yes	(64Mx4) *18	x4SB	
+Buffalo	DD266-R512/SD	K4H560838D-TCB0 rev D	Samsung	RCE0501-AB	1/10/03	2.5		(32Mx8) *18	x8DB	
+Dataram	DTM63641G	MT46V64M4TG-75 rev C	Micron	40581A rev A	2/3/03	2.5	Yes	(64Mx4) *18	x4SB	
+Avant Technology	AVM7264R38C5266K0-A	MT46V64M4TG-75 B rev B	Micron	50-1415-01 rev B	2/3/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Virtium Technology Inc	VM383L6420E-B0	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	2/6/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Ventura Technology Group	D52WPK31SV	K4H560438D-TCB0 rev D	Samsung	V218	2/11/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Corsair	CM73SD512RLP-2100/Y	NT5DS64M4AT-7K rev A	Nanya	50-00112 rev A	2/12/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
SimpleTech	ST72E4K64-A75EC	MT46V64M4TG-75 rev B	Micron	00853 rev B	2/19/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
+Avant Technology	AVM7264R38C2266K0-A	NT5DS64M4AT-7K rev A	Nanya	50-1415-01 rev B	2/25/03	2	Yes	(64Mx4) *18	x4SB	EOL
+Viking	VI4CR647224DTHL1	K4H560438D-TCB0 rev D	Samsung	03-0291 rev A	2/27/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Samsung	? M312L6420DT0-CAA	K4H560438D-TCAA	Samsung		12/8/02	2	Yes	(64Mx4) *18	x4SB	
+ATP Electronics	AB64L72Q8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1 rev 1	12/20/02	2.5	Yes	(32Mx8) *18	X8DB	EOL

Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Micron	MT18VDDT6472G-265C3	MT46V64M4-75 C	Micron		12/29/02	2.5	Yes	(64Mx4) *18	x4SB	
+Viking	VI4CR647228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000905AG	1/3/03	2.5	Yes	(32Mx8) *18	X8DB	EOL
Infineon	? HYS72D64500GR-7F-B	HYB25D256400BT-7F	Infineon		1/13/03	2	Yes	(64Mx4) *18	x4SB	
Infineon	HYS72D64500GR-7-A	HYB25D256400AT-7	Infineon		2/13/03	2	Yes	(64Mx4) *18	x4SB	
Southland Micro Systems	512L-RD266EB-D7	MT46V64M4TG-75 rev C	Micron	120712 rev C	3/17/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
+ATP Electronics	AB64L72R4S8B0S	K4H560438D-TCB0 rev D	Samsung	SB184R04L1	3/20/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Samsung	? M383L6420DTS-CAA	K4H560438D-TCAA	Samsung		3/24/03	2		(64Mx4) *18	x4SB	
Smart Modular Technologies	SM6472RDDR3H1LP-N	NT5DS64M4AT-7K	Nanya	P52G184NESZ6G001 rev A	3/31/03	2.5	Yes	(64Mx4) *18	x4SB	
Micron	MT18VDDT6472G-265B1	MT46V64M4-75 B	Micron		4/7/2003	2.5		(64Mx4) *18	x4SB	
+Viking	VI4CR647228DTHL2	K4H560838D-TCB0	Samsung	0000905A	4/10/03	2.5	Yes	(32Mx8) *18	X8DB	EOL
SimpleTech	ST72E4K64-A75EC	MT46V64M4TG-75 rev C	Micron	00853 rev B	4/24/03	2.5	Yes	(64Mx4) *18	x4SB	
+Buffalo	DD266-R512/MB	MT46V32M8-75 rev B	Micron	RCE0501-AB	4/28/03	2.5		(32Mx8) *18	X8DB	
Samsung	M383L6420ETS-CB0	K4H560438E-TCB0	Samsung		4/30/03	2.5		(64Mx4) *18	x4SB	
+Buffalo	DD266L-R512/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/30/03	2.5	Yes	(32Mx8) *18	X8DB	
+ATP Electronics	AB64L72A8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184A08L rev1	5/5/03	2.5		(32Mx8) *18	X8DB	EOL
Corsair	CM72SD512RLP-2100/M	MT46V32M8TG-75 rev C	Micron	50-00123 rev A	5/8/03	2.5	Yes	(32Mx8) *18	X8DB	
+Viking	VI4CR647228DTHL4	MT46V32M8TG-75 rev C	Micron	0000905A rev A	5/13/03	2.5	Yes	(32Mx8) *18	X8DB	
+Viking	VI4CR647224DTHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	5/20/03	2.5	Yes	(64Mx4) *18	x4SB	EOL
Samsung	M312L6420ETS-CA2	K4H560438E-TCA2	Samsung		5/27/03	2	Yes	(64Mx4) *18	X4SB	
Samsung	?M312L6420ETS-CAA	K4H560438E-TCAA	Samsung		6/9/03	2	Yes	(64Mx4) *18	X4SB	
Samsung	M312L6420DT0-CB0	K4H560438D-TCB0	Samsung		6/9/03	2.5	Yes	(64Mx4) *18	X4SB	
Infineon	HYS72D64320GBR-7-B	HYB25D256800BC-7	Infineon		6/18/03	2	Yes	(32Mx8) *18	X8DB	
+TRS* Tele-Radio-Space GmbH	TRS21151	HYB25D256400BT-7 rev B	Infineon	M0530LA1 rev 1	6/17/03	2	Yes	(64Mx4) *18	X4SB	

Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Legend	L6472YC5-PPASDC5D	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	6/23/03	2.5	Yes	(64Mx4) *18	X4SB	EOL
PMI USA Inc	MD6412RSA-T28AA	K4H560838D-TCB3	Samsung	BRDA80A	6/16/03	2.5	Yes	(32Mx8) *18	X8DB	
+TRS* Tele-Radio-Space GmbH	TRS21152	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/23/03	2	Yes	(32Mx8) *18	X8DB	
ITAUCOM	512E2665R24	ICM4L560407-65	Micron	0269 A	7/11/03	2.5	Yes	(64Mx4) *18	X4SB	
+Legend	L6472TC5-RR2HDC5A	HY5DU56822AT-H rev A	Hyundai	DRR720818A rev 2	7/1/03	2.5		(32Mx8) *18	X8DB	EOL
Micron	MT18VDDT6472G-262C3	MT46V64M4-75E C	Micron		7/14/03	2.5	Yes	(64Mx4) *18	X4SB	
+Smart Modular Technologies	SM6472RDDR320LP-I	HYB25D256400BT-7 rev B	Infineon	184-M12-2	7/21/03	2	Yes	(64Mx4) *18	X4SB	
+Smart Modular Technologies	SM6472RDDR3222L	HYB25D256400BT-7F rev B	Infineon	184-M12-2	8/11/03	2	Yes	(64Mx4) *18	X4SB	
Samsung	M383L6420DTS-CB0	K4H560438D-TCB0	Samsung		8/22/03	2.5		(64Mx4) *18	X4SB	
+Smart Modular Technologies	SM6472RDDR3H1LP1-S	K4H560838E-TCB0 rev E	Samsung	P52G184NEBZ6RCL rev B	8/26/03	2.5	Yes	(64Mx4) *18	X4SB	
Micron	MT18VDDF6472G-265C1	3NCII D9BHV	Micron		9/2/03	2.5	Yes	(64Mx4) *18	X4SB	
Infineon	HYS72D64000GR-7-B	HYB25D256400BT-7	Infineon		9/4/03	2		(64Mx4) *18	X4SB	
Infineon	? HYS72D64300GBR-7F-B	HYB25D256400BC-7F	Infineon		9/24/03	2	Yes	(64Mx4) *18	X4SB	
+Avant Technology	AVM7264R38C5266K0-A	NT5DS64M4BT-75B rev B	Nanya	50-1415-01-B rev B	9/15/03	2.5	Yes	(64Mx4) *18	X4SB	
+Smart Modular Technologies	SM6472RDDR301LP1-I	HYB25D256800BT-7 rev B	Infineon	P52G184NEBZ6RCL rev B	9/25/03	2	Yes	(32Mx8) *18	X8DB	
+Ventura Technology Group	D52WVK25SV	K4H560838E-TCB3 rev E	Samsung	V208	10/02/03	2.5	Yes	(32Mx8) *18	X8DB	
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	10/30/03	2.5	Yes	(32Mx8) *18	X8DB	
+Centon Electronics	TOP02-D019S	MT46V32M8TG-6 rev C	Micron	DR1G872-A	10/14/03	2.5	Yes	(32Mx8) *18	X8DB	
+ATP Electronics	AB64L72Q8S8B0S	K4H560838E-TCB3 rev E	Samsung	SB184Q08L1	10/16/03	2.5	Yes	(32Mx8) *18	X8DB	
+Legend	L6472YC5-182HDD5A	HY5DU56422AT-K rev A	Hyundai	184RL rev 2	10/24/03	2.5	Yes	(64Mx4) *18	X4SB	
+Smart Modular Technologies	SM6472RDDR325LP-S	K4H560438E-TCB0 rev E	Samsung	M312L3310ETS	10/21/03	2.5	Yes	(64Mx4) *18	X4SB	
Kingston	KVR266X72RC25/512	HYB25D256400BT-7	Infineon		11/5/03	2.5	Yes	(32Mx8) *18	X8DB	
+Legacy Electronics Inc.	88L6JDLR-1LDG	LED64408TA-6	Legacy	LE36DDT1844R rev A	11/24/03	2.5	Yes	(64Mx4) *18	X4SB	

Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Swissbit	SDR06472D1B22IN-75	HYB25D256800BT-6 rev B	Infineon	BRDA80A	2/24/04	2	Yes	(32Mx8)*18	X8DB	
+Ventura Technology Group	D52WVK25MV3	MT46V32M8TG-6T rev C	Micron	V208	3/12/04	2.5		(32Mx8)*18	X8DB	
Netlist, Incorporated	NL9647RD64042-D21JPA	V58C2256404SAT7 rev A	ProMOS	0197-10 rev A	3/19/04	2.5	Yes	(64Mx4)*18	X4SB	
+Viking	VI4CR647228DTHL5	MT46V32M8TG(P)-6T rev G	Micron	0000985A	5/25/04	2.5	Yes	(32Mx8)*18	X8DB	
+Legacy Electronics Inc.	88S6JDLR-1JDG	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	5/13/04	2	Yes	(64Mx4)*18	X4SB	
+Ventura Technology Group	D52WVK42SV	K4H560838E-TCB3 rev E	Samsung	DR1G872-A	6/3/04	2.5	Yes	(32Mx8)*18	X8DB	
+Dane-Elec	DLD266R072642H	HYB25D256400BT-7 rev B	Infineon	0303	7/14/04	2	Yes	(64Mx4)*18	X4SB	

Modules shaded in blue are low profile

? This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards. For further information contact CMTL @ http://cmtlabs.com/

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Samsung	M312L2828DT0-CA2	K4H560438D-TCA2	Samsung		10/17/02	2	Yes	(64Mx4)*36	x4DB	
Apacer	Apacer 75.06280.792	HYB25D256400BT-7	Infineon		10/27/02	2	Yes	(64Mx4)*36	x4DB	
Samsung	M312L2828DT0-CB0	K4H510638D-TCB0	Samsung		12/2/02	2.5	Yes	(64Mx4)*36	x4DB	
+MSC Vertriebs GmbH	MSC001G00096	HYB25D512800AT-7 rev A	Infineon	M0481LA2	12/11/02	2		(64Mx8)*18	x8DB	EOL
+Dataram	DTM63621F	HYB25D256400BT-7 rev B	Infineon	40556 rev B	12/12/02	2	Yes	(64Mx4)*36	x4DB	EOL
Samsung	M383L2828DT1-CA2	K4H560438D-TCA2	Samsung		12/13/02	2		(64Mx4)*36	x4DB	
Netlist	NL9127RD64042-D21J	K4H560438C-TCB0	Samsung		12/23/02	2.5		(64Mx4)*36	x4DB	
Infineon	HYS72D128320GBR-7-B	HYB25D256400BC-7	Infineon		1/1/03	2	Yes	(64Mx4)*36	x4DB	
+Avant Technology	AVM7228R82C2266K1-A	NT5DS64M4AT-7K rev A	Nanya	50-1416-01-A rev A	1/22/03	2	Yes	(64Mx4)*36	x4DB	EOL
Samsung	? M312L2828DT0-CAA	K4H510638D-TCAA	Samsung		1/29/03	2	Yes	(64Mx4)*36	x4DB	
+Dataram	DTM63653C	K4H560438D-GCA2 rev D	Samsung	40599A rev A	2/3/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
Infineon	HYS72D128500GR-7-A	HYB25D512400AT-7	Infineon		2/5/03	2	Yes	(64Mx8)*18	x8DB	
Corsair	CM74SD1024RLP-2100/Y	NT5DS64M4AT-7K rev A	Nanya	50-00115 rev A	2/7/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72T4SQB0S	K4H560438D-TCB0 rev D	Samsung	SB184T04 L2 rev 2	2/13/03	2.5		(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72P4SMB0A	NT5DS64M4AT-7K	Nanya	SB184P04 L1 rev 1	2/18/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Aved Memory Products	AMP383D2827DT1-CB0/S	K4H560438D-TCB0 rev D	Samsung	105605 rev A	2/18/03	2.5		(64Mx4)*36	x4DB	EOL
Infineon	HYS72D128521GR-7-B	HYB25D256400BT-7	Infineon		2/20/03	2	Yes	(64Mx4)*36	x4DB	
+Dataram	DTM63653B	HYB25D256400BC-7 rev B	Infineon	40599A rev A	2/28/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Avant Technology	AVM7228R38C2266K3-A	NT5DS64M4AT-7K rev A	Nanya	BRDB45A rev A	3/6/03	2		(64Mx4)*36	x4DB	EOL
Infineon	? HYS72D128521GR-7F-B	HYB25D256400BT-7F	Infineon		3/12/03	2	Yes	(64Mx4)*36	x4DB	
+Dataram	DTM63621H	MT46V64M4TG-75 rev C	Micron	40556 rev B	3/17/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72T4SQA2	NT5DS64M4AT-7K	Nanya	SB184T04 L2 rev 2	3/19/03	2.5		(64Mx4)*36	x4DB	EOL
Southland Micro Systems	1GBL-RD266EB-D7	MT46V64M4TG-75 rev C	Micron	120712 rev C	3/20/03	2.5	Yes	(64Mx4)*36	x4DB	EOL

Registered, ECC, DDR266 DIMM Modules
1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Avant Technology	AVM7228R38C5266K3-A	MT46V64M4TG-75 B rev B	Micron	BRDB45A rev A	3/31/03	2.5		(64Mx4) *36	x4DB	EOL
+Avant Technology	AVM7228R38C5266K3-A	K4H560438D-TCB0 rev D	Samsung	BRDB45A rev A	3/27/03	2.5		(64Mx4) *36	x4DB	EOL
+ATP Electronics	AB28L72P4SUB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1	4/4/03	2.5	Yes	(64Mx4) *36	x4DB	EOL
Micron	MT36VDDT12872G-265C2	MT46V64M4TG-75 rev C	Micron	0232 rev A	4/1/03	2.5	Yes	(64Mx4) *36	x4DB	EOL
+ATP Electronics	AB28L72P4SMB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1	4/4/03	2.5	Yes	(64Mx4) *36	x4DB	EOL
Netlist	NL9127RD64052-D21J	K4H560438D-TCB0	Samsung		4/9/03	2.5	Yes	(64Mx4) *36	x4DB	
+Centon Electronics	TOP02-D006F	MT46V64M4TG-75C rev C	Micron	LE36DDT1844R rev A	4/10/03	2.5	Yes	(64Mx4) *36	x4DB	EOL
+SimpleTech	ST72E4L128-A75EC	MT46V64M4TG-75 rev C	Micron	00853 rev B	4/30/03	2.5	Yes	(64Mx4) *36	x4DB	
Samsung	M312L2920MT0-CB0	K4H510438M-TCB0	Samsung		5/15/03	2.5	Yes	(128Mx4) *18	X4SB	
+Smart Modular Technologies	SM12872RDDR301LP-N	17329-02	Nanya	P51G184NESZK002 rev A	5/30/03	2	Yes	(64Mx4) *36	x4DB	
Infineon	? HYS72D128320GBR-7F-B	HYB25D256400BC-7F	Infineon		6/18/03	2	Yes	(64Mx4) *36	x4DB	
Centon Electronics	TOP02-C002B	MT46V64M4TG-75 rev B	Micron	LE36DDT1844R rev A	6/11/03	2.5	Yes	(64Mx4) *36	x4DB	
PMI USA Inc	MD641GREP-TG8AA	DD5108ABTA-7A	Elpida	BRDA80A	6/26/03	2.5	Yes	(64Mx8) *18	x8DB	
Samsung	M312L2828ET0-CA2	K4H510638E-TCA2	Samsung		7/01/03	2	Yes	(64Mx4)*36	x4DB	
Samsung	M383L2828ET1-CB0	K4H510638E-TCB0	Samsung		7/08/03	2.5		(64Mx4)*18	x4DB	
+Smart Modular Technologies	SM12872RDDR3H1LP-S	K4H510638D-TCB0 rev D	Samsung	M312L2828T0	7/10/03	2.5	Yes	(64Mx4) *36	x4DB	
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	7/18/03	2	Yes	(64Mx4) *36	x4DB	
ITAUCOM	01GE2665R24	MT46V64M4TG-75 rev C	Micron	0232 A	7/15/03	2.5	Yes	(64Mx4) *36	x4DB	
+Legend	L1272YC5-PPBSDD5D	K4H560438D-TCB0 rev D	Samsung	18-21040B rev B	7/1/03	2.5	Yes	(64Mx4) *36	x4DB	EOL
Micron	MT36VDDT12872G-265C2	MT46V64M4-75 C	Micron		7/22/03		Yes	(64Mx4) *36	x4DB	
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	7/18/03	2.5	Yes	(64Mx4) *36	x4DB	
Micron	MT36VDDT12872G-262C3	MT46V64M4FG-75E	Micron		8/18/03	2	Yes	(64Mx4) *36	x4DB	
+Centon Electronics	TOP02-D018R	MT46V64M4TG-6T rev C	Micron	LE36DDT1844R rev A	8/2/03	2	Yes	(64Mx4) *36	x4DB	

Registered, ECC, DDR266 DIMM Modules
1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Samsung	? M312L2828ET0-CAA	K4H510638E-TCAA	Samsung		8/22/03	2	Yes	(64Mx4) *36	x4DB	
+Centon Electronics	TOP02-D023W	HYB25D256400BT-7 rev B	Infineon	LE36DDT1 844R rev A	9/2/03	2.5	Yes	(64Mx4) *36	x4DB	
+Ventura Technology Group	D54WPK28SV	K4H560438E-TCB0 rev E	Samsung	V213	9/8/03	2.5		(64Mx4) *36	x4DB	
+TRS* Tele-Radio-Space GmbH	TRS21153	HYB25D256400BT-7 rev B	Infineon	M0531LA1 rev 1	9/19/03	2	Yes	(64Mx4) *36	x4DB	
Wintec Industries	35952756L	HYB25D256400AT-7 rev A	Infineon	ZK2048M84 RBYJ	10/3/03	2.5	Yes	(64Mx4) *36	x4DB	
Virtium Technology Inc	VM383L2826E-B0S	K4H560438D-TCB3 rev D	Samsung	18-21040B rev B	9/29/03	2.5	Yes	(64Mx4) *36	x4DB	
+Legend	L1272YC5-183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3	10/9/03	2.5	Yes	(64Mx4) *36	x4DB	
+Smart Modular Technologies	SM12872RDDR301 LP-I	HYB25D256400BT-7 rev B	Infineon	P54G184N ESZKRCN rev A	11/5/03	2	Yes	(64Mx4) *36	x4DB	
+Viking	VI4CR287224DYHL 3	MT46V64M4TG-75 rev C	Micron	03-0291 rev A	10/16/03	2.5	Yes	(64Mx4) *36	x4DB	
+Avant Technology	AVM7228R82C5266K1-A	NT5DS64M4BT-75B rev B	Nanya	50-1416-01-A rev A	10/22/03	2.5	Yes	(64Mx4) *36	x4DB	
+Avant Technology	AVM7228R38C5266K3-A	NT5DS64M4BT-75B rev B	Nanya	BRDB45A rev A	10/21/03	2.5		(64Mx4) *36	x4DB	
+Legacy Electronics Inc.	89L6MDLR-1LDG	LED128408TA-6	Legacy	LE36DDT1 844R rev A	11/13/03	2.5	Yes	(128Mx4)	X4SB	
+ATP Electronics	AB28L72P4SMB0S	K4H560438E-TCB0 rev E	Samsung	SB184P04L 1	11/13/03	2.5	Yes	(64Mx4) *36	x4DB	
+ATP Electronics	AB28L72U4SQB0S	K4H560438E-TCB0 rev E	Samsung	SB184U04L 1	12/04/03	2.5		(64Mx4) *36	x4DB	
+ATP Electronics	AB28L72T4SQB0S	K4H560438E-TCB0 rev E	Samsung	SB184T04L 2	12/02/03	2.5		(64Mx4) *36	x4DB	EOL
+Apacer	77.11342.112	HYB25D256400BT-7 rev B	Infineon	48.18121.012 rev 2	12/02/03	2	Yes	(64Mx4) *36	x4DB	
+Legend	L1272YC5-RU1HDH5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818-A rev 1	12/10/03	2.5	Yes	(64Mx8) *18	x8DB	
+Smart Modular Technologies	SM12872RDDR301 BG-I	HYB25D256400BC-6 rev B	Infineon	P54G184N ESZBRCD rev A	12/17/03	2	Yes	(64Mx4) *36	x4DB	
PMI USA Inc	MD641GRSA-TG8AA	K4H510838B-TCB3 rev B	Samsung	BRDA80A	1/22/04	2.5	Yes	(64Mx8) *18	x8DB	
+Centon Electronics	TOP02-D026Z	MT46V64M8TG-6T rev C	Micron	DR1G872-A	1/13/04	2.5	Yes	(64Mx8) *18	x8DB	
+Smart Modular Technologies	SM12872RDDR301 HP-I	HYB25D256400BT-7 rev B	Infineon	P58G184N ESZKGA1	2/3/04	2		(64Mx4) *36	x4DB	
+Swissbit	SDR12872C1A22IN-70	HYB25D256400BC-7 rev B	Infineon	B6R400	2/17/04	2	Yes	(64Mx4) *36	x4DB	
+Buffalo	DD266L-RW1G/SE	K4H560438E-TCB0 rev E	Samsung	4D248EF-AA	1/28/04	2.5	Yes	(64Mx4) *36	x4DB	

Registered, ECC, DDR266 DIMM Modules
1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Smart Modular Technologies	SM12872RDDR3H2LP-S	K4H560438E-TCB0 rev E	Samsung	P54G184NESZKRCN rev A	2/27/04	2.5	Yes	(64Mx4) *36	x4DB	
+TRS	TRS21174	HYB25D512800AT-7 rev A	Infineon	M0529LA1 rev 1	2/20/04	2	Yes	(64Mx8) *18	x8DB	
+TRS	TRS21171	HYB25D256400BC-7 rev B	Infineon	M0533LA1 rev 1	3/4/04	2	Yes	(64Mx4) *36	x4DB	
+Ventura Technology Group	D54WCK34SV	K4H560438E-GCB3 rev E	Samsung	V223	3/12/04	2.5	Yes	(64Mx4) *36	x4DB	
+Dataram	DTM63686A	HYB25D256400BT-7 rev B	Infineon	40028A rev A	3/5/04	2		(64Mx4) *36	x4DB	
+Dataram	DTM63653H	HYB25D256400BC-6 rev B	Infineon	40599A rev A	3/9/04	2	Yes	(64Mx4) *36	x4DB	
Samsung	M312L2828ET0-CB0	K4H510638E-TCB0	Samsung		3/17/04	2.5	Yes	(64Mx4) *36	x4DB	
+Ventura Technology Group	D54WYK25SV	K4H510838B-TCB3 rev B	Samsung	V208	3/19/04	2.5		(64Mx8) *18	x8DB	
+Legacy Electronics Inc.	89S6JDLC-1JDG	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	4/13/04	2	Yes	(64Mx4) *36	x4DB	
+Smart Modular Technologies	SM12872RDDR301BGAS	K4H560438E-GCB3 rev E	Samsung	P54G184NESZBRCD	4/13/04	2	Yes	(64Mx4) *36	x4DB	
+Viking	VI4CR287228ETHL1	MT46V64M8TG(P)-75 rev D	Micron	0000985A	4/21/04	2.5	Yes	(64Mx8) *18	x8DB	
+ATP Electronics	AB28L72Q8SHB0S	K4H510838B-TCB3 rev B	Samsung	SB184Q08L1 rev 1	4/29/04	2.5	Yes	(64Mx8) *18	x8DB	
+Legacy Electronics Inc.	89L6JDGR-1LDG	LED64408TA-6 rev B	Legacy	LE36DDF1844RLP rev A	4/21/04	2.5	Yes	(64Mx4) *36	x4DB	
Micron	MT36VDDF12872G-265C3	3RC11-D9BHV	Micron		2/19/04	2.5	Yes	(64Mx4) *36	x4DB	
Infineon	HYS72D128021GR-7-B	HYB25D256400BT-7	Infineon		3/17/04	2		(64Mx4) *36	x4DB	
Corsair	CM72SD1024RLP-2100/S	K4H510838B-TCB3 rev B	Samsung	50-00123A rev A	5/25/04	2.5	Yes	(64Mx8) *18	x8DB	
Samsung	M312L2920BTS-CB0	K4H510438B-TCB0	Samsung		5/19/04	2.5	Yes	(128Mx4) *18	X4SB	
Infineon	HYS72D128300GBR-6-B	HYB25D512400BC-6	Infineon		5/22/04	2.5	Yes	(128Mx4) *18	X4SB	
Kingston	KVR266X72RC25/1024	K4H510438B-TCB0 rev B	Samsung	2025127-001.A00	6/14/04	2.5	Yes	(128Mx4) *18	X4SB	
+Dataram	DTM63698B	HYB25D512400BE-7 rev B	Infineon	40581A rev A	7/16/04	2	Yes	(128Mx4) *18	X4SB	

Modules shaded in blue are low profile

? This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards. For further information contact CMTL @ http://cmtlabs.com/

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Server Board SE7501WV2

Registered, ECC, DDR266 DIMM Modules

2G Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Rank	EOL
Samsung	M383L5628MT1-CA2	K4H510438M-TCA2	Samsung		11/6/02	2		(128Mx4) *36	x4DB	
Samsung	M312L5628MT0-CB0	K4H1G0638M-TCB0	Samsung		12/26/02	2.5	Yes	(128Mx4) *36	x4DB	
Infineon	HYS72D256520GR-7-A	HYB25D512400AT-7	Infineon		02/20/03	2	Yes	(128Mx4) *36	x4DB	
Infineon	? HYS72D256520GR-7F-A	HYB25D512400AT-7F	Infineon		5/14/03	2	Yes	(128Mx4) *36	x4DB	
+Smart Modular Technologies	SM25672RDDR301LP-I	HYB25D512400AT-7 rev A	Infineon	P54G184NESZKRCN rev A	5/22/03	2	Yes	(128Mx4) *36	x4DB	
+TRS* Tele-Radio-Space GmbH	TRS21155	HYB25D512400AT-7 rev A	Infineon	M0531LA1 rev 1	9/17/03	2	Yes	(128Mx4) *36	x4DB	
+Avant Technology	AVM7256R83C5266K1-A	MT46V128M4TG-75 rev C	Micron	50-1416-01-A rev A	10/24/03	2.5	Yes	(128Mx4) *36	x4DB	
+Smart Modular Technologies	SM25672RDDR301HP-I	HYB25D512400AT-7 rev A	Infineon	P52G184NESZKGA1	11/6/03	2		(128Mx4) *36	x4DB	
+Dataram	DTM63663B	HYB25D512400AT-7 rev A	Infineon	40556 rev B	10/27/03	2	Yes	(128Mx4) *36	x4DB	
+Legacy Electronics Inc.	8AL6MDLC-1LDG	LED128408TA-6	Legacy	LE36DDT1844R rev A	11/19/03	2.5	Yes	(128Mx4) *36	x4DB	
+ATP Electronics	AB56L72P4SMB0M	MT46V128M4TG-75 rev C	Micron	SB184P04L1	1/16/04	2.5	Yes	(128Mx4) *36	x4DB	
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung		2/12/04	2.5	Yes	(128Mx4)*36	x4DB	
+Dataram	DTM63689A	MT46V128M4FN-6 rev C	Micron	40020A rev A	2/9/04	2	Yes	(128Mx4) *36	x4DB	
Micron	MT36VDDF25672G-265C2	MT46V128M4FN-75	Micron	0328 rev A	2/17/04	2.5	Yes	(128Mx4)*36	x4DB	
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213	3/26/04	2.5		(128Mx4)*36	x4DB	
+Legacy Electronics Inc.	8AS6MDLC-1JDG	HYB25D512400AT-7 rev A	Infineon	LE36DDT1844R	4/29/04	2	Yes	(128Mx4)*36	x4DB	
Micron	MT36VDDF25672G-26AC2	3YCII D9BXK	Micron		3/2/04	2.5	Yes	(128Mx4)*36	x4DB	
Samsung	M383L5628BT1-CA2	K4H510438M-TCA2	Samsung		3/10/04	2		(128Mx4)*36	x4DB	
Kingston	KVR266X72RC25/2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00	6/24/04	2.5	Yes	(128Mx4)*36	x4DB	

Modules shaded in blue are low profile

? This is a 2-2-2 part.

When 2GB DIMM's are used with the Intel® Server Board SE7501WV2 integrated into the Intel Server Chassis SR1300 & SR2300, Intel's thermal testing results show that operating these server system configurations at an ambient inlet temperature of 35 degrees Celsius may potentially cause internal system components to exceed their maximum specified operating temperatures. Intel has verified that internal system components do not exceed their maximum specified operating temperatures when the Intel Server Chassis SR1300 server system configurations are operated at a maximum ambient inlet temperature of 30 degrees C. Intel has also verified that internal system components do not exceed their

maximum specified operating temperatures when the Intel Server Chassis SR2300 server system configurations are operated using the "Optional Memory Cooling Enhancement Fan Accessory, Product Code: FSWMEMFAN, MM#: 852787" available from Intel. For additional information see TA656-1.

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards. For further information contact CMTL @ http://cmtlabs.com/

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpusa.com/	Florence Hsieh Tel 408-732-5831 Fax 408-732-5055 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpusa.com/	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA phenke@dataram.com Peter Jauss, +49-69-680-9070 in EMEA pjauss@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
Infineon	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itaucom.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Keri Albers 888 466 3853 ext. 307 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/'http://silicon.micron.com/mktg/mbqual/qual_data.cfm	

Vendor Name	Web URL	Vendor Direct Sales Info
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements	http://www.peripheral.com/	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	http://www.smartm.com	Leo Alafriz 949-753-0116 ext. 125 leo.alafriz@smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http:/www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gründl, Pho.: +49(0)89/94553234, Fax.: +49(0)89/94553293, agruendl@trs-space.de
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Don Hummel @ 805-581-0800 x 108 or email @ don@venturatech.com
Viking InterWorks	http://www.vikinginterworks.com	
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Legend	http://www.legend.com.au	Tel: 800-338-2361 Fax: 949-459-8577 orderdesk@vikingcomponents.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.